

PATENT ASSIGNMENT COVER SHEET

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 Stylesheet Version v1.2

EPAS ID: PAT2719618

SUBMISSION TYPE:	NEW ASSIGNMENT
NATURE OF CONVEYANCE:	RELEASE BY SECURED PARTY
CONVEYING PARTY DATA	
Name	Execution Date
DOWA ELECTRONICS MATERIALS CO., LTD.	02/10/2014
RECEIVING PARTY DATA	
Name:	PCHEM ASSOCIATES, INC.
Street Address:	3599 MARSHALL LANE
Internal Address:	SUITE D
City:	BENSALEM
State/Country:	PENNSYLVANIA
Postal Code:	19020
PROPERTY NUMBERS Total: 11	
Property Type	Number
Patent Number:	7931941
Application Number:	11613136
Patent Number:	7763362
Application Number:	12501440
Application Number:	12714430
Application Number:	13321675
Application Number:	61155909
Application Number:	61437624
PCT Number:	US2006048699
PCT Number:	US2008055446
PCT Number:	US2009050389
CORRESPONDENCE DATA	
Fax Number:	(703)770-7901
Phone:	703-770-7900

Email: jennifer.sallee@pillsburylaw.com
Correspondence will be sent via US Mail when the email attempt is unsuccessful.
Correspondent Name: PILLSBURY WINTHROP SHAW PITTMAN LLP
Address Line 1: P.O. BOX 10500
Address Line 4: MCLEAN, VIRGINIA 22102

ATTORNEY DOCKET NUMBER:	028028-0000009
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NAME OF SUBMITTER:	JENNIFER E. SALLEE
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Signature:	/Jennifer E. Sallee/
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Date:	02/10/2014
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Total Attachments: 3 source=Release#page1.tif source=Release#page2.tif source=Release#page3.tif
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Release

Dated February 10, 2014

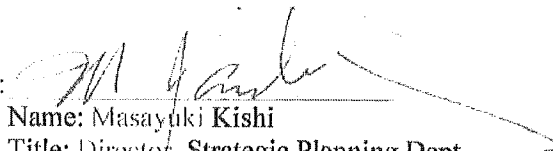
Reference is hereby made to the two Loan Agreements, dated as of October 10, 2011, between PChem Associates, Inc., ("Borrower") and Dowa Electronics Materials Co., Ltd. ("Lender"), and recorded in the United States Patent and Trademark Office at Reel/Frame 027172/0855 and 027172/0774 and again at Reel/Frame 027663/0082 and 027663/0146.

The Lenders hereby release the lien on and security interest in any and all right, title and interest in and to those patent and trademark properties listed in Schedule 1, attached (the "Released Collateral").

[Signature Page Follows]

IN WITNESS WHEREOF, the Lender has duly executed this Release on the date first written above.

Dowa Electronics Materials Co., Ltd.

By: 
Name: Masayuki Kishi
Title: Director, Strategic Planning Dept.

Schedule I

Application No.	Filing Date	Title	Patent No.	Issue Date
11/261,313	10/29/2005	SYNTHESIS OF METALLIC NANOPARTICLE DISPERSIONS CAPABLE OF SINTERING AT LOW TEMPERATURES	7,931,941	4/26/2011
11/613,136	12/19/2006	SYNTHESIS OF METALLIC NANOPARTICLE DISPERSIONS		
12/039,896	02/29/2008	SHIELDING BASED ON METALLIC NANOPARTICLE COMPOSITIONS AND DEVICES AND METHODS THEREOF	7,763,362	7/27/2010
12/501,440	7/12/2009	METALLIC NANOPARTICLE SHIELDING STRUCTURE AND METHODS THEREOF		
12/714,430	2/26/2010	METHODS FOR FABRICATING ANALYTICAL SUBSTRATES USING METALLIC NANOPARTICLES		
13/321,675	11/21/2011	LOW-TEMPERATURE SINTERED SILVER NANOPARTICLE COMPOSITION AND ELECTRONIC ARTICLES FORMED USING THE SAME		
61/155,909	2/26/2009	METHODS AND SYSTEMS FOR APPLYING METALLIC NANOPARTICLE-BASED INKS TO CREATE AN ANALYTICAL SUBSTRATE		
61/437,624	1/29/2011	METHODS AND SYSTEMS FOR GENERATING A SUBSTANTIALLY TRANSPARENT AND CONDUCTIVE SUBSTRATE		
PCT/US2006/048699	12/20/2006	SYNTHESIS OF METALLIC NANOPARTICLE DISPERSIONS		
PCT/US2008/055446	2/29/2008	SHIELDING BASED ON METALLIC NANOPARTICLE COMPOSITIONS AND DEVICES AND METHODS THEREOF		
PCT/US2009/050389	7/13/2009	METALLIC NANOPARTICLE SHIELDING STRUCTURE AND METHODS THEREOF		

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